2.5/3.3V 200-MHz Multi-Output Zero Delay Buffer

Features

- **2.5V or 3.3V operation**
- **Split output bank power supplies**
- **Output frequency range: 6 MHz to 200 MHz**
- **Output-output skew: < 150 ps**
- **Cycle-cycle jitter: < 100 ps**
- **Selectable positive or negative edge synchronization**
- **8 LVTTL outputs driving 50Ω terminated lines**
- **LVCMOS/LVTTL over-voltage tolerant reference input**
- **Selectable phase-locked loop (PLL) frequency range and lock indicator**
- **(1-6,8,10,12)x multiply and (1/2,1/4)x divide ratios**
- **Spread-Spectrum-compatible**
- **Power-down mode**
- **Industrial temperature range: –40°C to +85°C**
- **44-pin TQFP package**

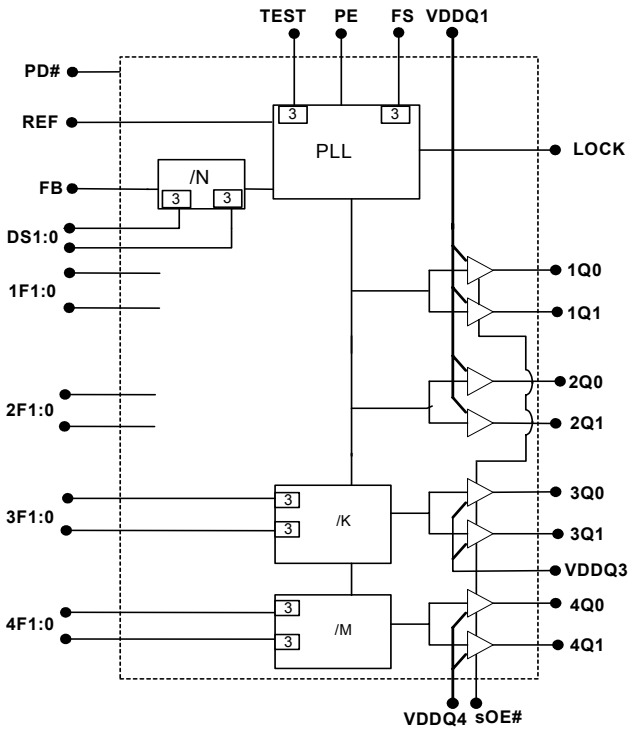
Description

The CY2V995 is a low-voltage, low-power, eight output, 200-MHz clock driver. It features function necessary to optimize the timing of high-performance computer and communication systems.

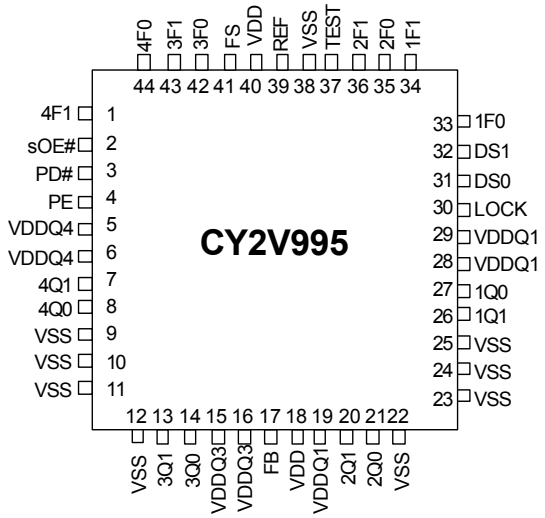
The user can program the frequency of the output banks through nF[0:1] and DS[0:1] pins. Any one of the outputs can be connected to feedback input to achieve different reference frequency multiplication and divide ratios and zero input-output delay.

The device also features split output bank power supplies which enable the user to run two banks (1Qn and 2Qn) at a power supply level different from that of the other two banks (3Qn and 4Qn). Additionally, the PE pin controls the synchronization of the output signals to either the rising or the falling edge of the reference clock.

Block Diagram



Pin Configuration



Pin Description

Pin	Name	I/O[1]	Type	Description
39	REF	I	LVTTL/ LVCMOS	**Reference Clock Input**.
17	FB	I	LVTTL	**Feedback Input**.
37	TEST	I	3-Level	**When MID or HIGH, disables PLL (except for conditions of note 3)**. REF goes to all outputs. Set LOW for normal operation.
2	sOE#	I, PD	LVTTL	**Synchronous Output Enable**. When HIGH, it stops clock outputs (except 2Q0 and 2Q1) in a LOW state (for PE = H or M) – 2Q0 and 2Q1 may be used as the feedback signal to maintain phase lock. When TEST is held at MID level and sOE# is high, the nF[1:0] pins act as output disable controls for individual banks when nF[1:0] = LL. Set sOE# LOW for normal operation.
4	PE	I, PU	LVTTL	**Selects Positive or Negative Edge Control and High or Low output drive strength**. When LOW / HIGH the outputs are synchronized with the negative/positive edge of the reference clock, respectively. Please see *Table 8*.
34, 33, 36, 35, 43, 42, 1, 44	nF[1:0]	I	3-Level	**Select frequency of the outputs**. Please see *Tables 3*, *4*, *5*, and *7*.
41	FS	I	3-Level	**Selects VCO operating frequency range**. Please see *Table 6*.
26,27,20,21, 13,14,7,8	nQ[1:0]	O	LVTTL	**Four banks of two outputs**. Please see *Table 5* for frequency settings.
32, 31	DS[1:0]	I	3-Level	**Select feedback divider**. Please see *Table 1*.
3	PD#	I, PU	LVTTL	**Power-down and reference divider control**. When LOW, shuts off entire chip. Please see *Table 2* for settings.
30	LOCK	O	LVTTL	**PLL lock indication signal**. HIGH indicates lock. LOW indicates that the PLL is not locked and outputs may not be synchronized to the input.
5,6	$V_{DD}Q4$[2]	PWR	Power	**Power supply for Bank 4 output buffers**. Please see *Table 8* for supply level constraints
15,16	$V_{DD}Q3$ [2]	PWR	Power	**Power supply for Bank 3 output buffers**. Please see *Table 8* for supply level constraints
19,28	$V_{DD}Q1$[2]	PWR	Power	**Power supply for Bank 1 and Bank 2 output buffers**. Please see *Table 8* for supply level constraints
18,40	V_{DD}[2]	PWR	Power	**Power supply for the internal circuitry**. Please see *Table 8* for supply level constraints
9-12, 22-25, 38	V_{SS}	PWR	Power	Ground

Device Configuration

The outputs of the CY2V995 can be configured to run at frequencies ranging from 6 MHz to 200 MHz. The feedback input divider is controlled by the 3-level DS[0:1] pins as indicated in *Table 1*.

Table 1. Feedback Divider Settings

DS[1:0]	N-Feedback Input Divider	Permitted Output Divider Connected to FB[4]
LL	2	1 or 2
LM	3	1
LH	4	1,2 or 4
ML	5	1 or 2
MM	1	1,2 or 4
MH	6	1 or 2
HL	8	1 or 2
HM	10	1
HH	12	1

Notes:

1. 'PD' indicates an internal pull-down and 'PU' indicates an internal pull-up.
2. A bypass capacitor (0.1µF) should be placed as close as possible to each positive power pin (<0.2"). If these bypass capacitors are not close to the pins their high frequency filtering characteristic will be cancelled by the lead inductance of the traces.
3. When TEST = MID and sOE# = HIGH, PLL remains active with nF[1:0] = LL functioning as an output disable control for individual output banks. Skew selections remain in effect unless nF[1:0] = LL.
4. Permissible output division ratios connected to FB. The frequency of the REF input will be F_{NOM}/N when the part is configured for frequency multiplication by using an undivided output for FB and setting DS[1:0] to N (N = 1-6, 8, 10, 12).

Table 2. Power-down Mode

PD#	CY2V995
H	Enabled
L	Power Down

In addition to the feedback dividers, the CY2V995 includes output dividers on Bank3 and Bank4, which are controlled by 3F[1:0] and 4F[1:0] as indicated in *Table 3* and *4*, respectively.

Table 3. Output Divider Settings – Bank 3

3F[1:0]	K – Bank3 Output Divider
LL[5]	2
HH	4
Other	1

Table 4. Output Divider Settings – Bank 4

4F[1:0]	M – Bank4 Output Divider
LL[5]	2
HH	Inverted[6]
Other	1

The divider settings, output frequencies, and possible configurations of connecting FB to ANY output are summarized in *Table 5*.

Table 5. Output Frequency Settings

Configuration	Output Frequency		
FB Input Connected to	1Q[0:1] and 2Q[0:1][7]	3Q[0:1]	4Q[0:1]
1Qn or 2Qn	N x F_{REF}	N /x (1 / K) x F_{REF}	N x (1 / M) x F_{REF}
3Qn	N x K x F_{REF}	N x F_{REF}	N x (K / M) x F_{REF}
4Qn	N x M x F_{REF}	N x (M / K) x F_{REF}	N x F_{REF}

The 3-level FS control pin setting determines the nominal operating frequency range of the divide-by-one outputs of the device. The CY2V995 PLL operating frequency range that corresponds to each FS level is given in *Table 6*.

Table 6. Frequency Range Select

FS	PLL Frequency Range
L	24 to 50 MHz
M	48 to 100 MHz
H	96 to 200 MHz

The PE pin determines Whether the outputs synchronize to the rising or the falling edge of the reference signal, as indicated in *Table 7*.

Table 7. PE Settings

PE	Synchronization
L	Negative
H	Positive

The CY2V995 features split power supply buses for Banks 1 and 2, Bank 3 and Bank 4, which enables the user to obtain both 3.3V and 2.5V output signals from one device. The core power supply (V_{DD}) must be set a level which is equal or higher than that on any one of the output power supplies.

Table 8. Power Supply Constraints

V_{DD}	$V_{DD}Q1$[8]	$V_{DD}Q3$[8]	$V_{DD}Q4$[8]
3.3V	3.3V or 2.5V	3.3V or 2.5V	3.3V or 2.5V
2.5V	2.5V	2.5V	2.5V

Governing Agencies

The following agencies provide specifications that apply to the CY2V995. The agency name and relevant specification is listed below.

Agency Name	Specification
JEDEC	JESD 51 (Theta JA)
	JESD 65 (Skew, Jitter)
IEEE	1596.3 (Jiter Specs)
UL-194_V0	94 (Moisture Grading)
MIL	883E Method 1012.1 (Therma Theta JC)

Notes:

5. LL disables outputs if TEST = MID and sOE# = HIGH.
6. When 4Q[0:1] are set to run inverted (HH mode), sOE# disables these outputs HIGH when PE = HIGH or MID, sOE# disables them LOW when PE = LOW.
7. These outputs are undivided copies of the VCO clock. Therefore, the formulas in this column can be used to calculate the VCO operating frequency (F_{NOM}) at a given reference frequency (F_{REF}) and divider and feedback configuration. The user must select a configuration and a reference frequency that will generate a VCO frequency that is within the range specified by FS pin. Please see *Table 6*.
8. $V_{DD}Q1/3/4$ must not be set at a level higher than that of V_{DD}. They can be set at different levels from each other, e.g. V_{DD} = 3.3V, $V_{DD}Q1$ = 3.3V, $V_{DD}Q3$ = 2.5V and $V_{DD}Q4$ = 2.5V.

Absolute Maximum Conditions

Parameter	Description	Condition	Min.	Max.	Unit
V_{DD}	Operating Voltage	Functional @ 2.5V ± 5%	2.25	2.75	V
V_{DD}	Operating Voltage	Functional @ 3.3V ± 10%	2.97	3.63	V
$V_{IN(MIN)}$	Input Voltage	Relative to V_{SS}	V_{SS} – 0.3	–	V
$V_{IN(MAX)}$	Input Voltage	Relative to V_{DD}	–	V_{DD} + 0.3	V
$V_{REF(MAX)}$	Reference Input Voltage	V_{DD} = 3.3V		5.5	V
$V_{REF(MAX)}$	Reference Input Voltage	V_{DD} = 2.5V		4.6	V
T_S	Temperature, Storage	Non Functional	–65	+150	°C
T_A	Temperature, Operating Ambient	Functional	–40	+85	°C
T_J	Temperature, Junction	Functional	–	155	°C
ESD_{HBM}	ESD Protection (Human Body Model)	MIL-STD-883, Method 3015	2000	–	V
$Ø_{JC}$	Dissipation, Junction to Case	Mil-Spec 883E Method 1012.1	42		°C/W
$Ø_{JA}$	Dissipation, Junction to Ambient	JEDEC (JESD 51)	74		°C/W
UL-94	Flammability Rating	@1/8 in.	V – 0		
MSL	Moisture Sensitivity Level		1		
F_{IT}	Failure in Time	Manufacturing Testing	10		ppm

DC Specifications @ 2.5V

Parameter	Description	Conditions		Min.	Max.	Unit
V_{DD}	2.5 Operating Voltage	2.5V ± 5%		2.375	2.625	V
V_{IL}	Input LOW Voltage	REF, FB, PE, PD#, and sOE# Inputs		–	0.7	V
V_{IH}	Input HIGH Voltage			1.7	–	V
V_{IHH}[9]	Input HIGH Voltage	3-Level Inputs (TEST, FS, nF[1:0], DS[1:0]) (These pins are normally wired to VDD,GND or unconnected)		V_{DD}– –0.4	–	V
V_{IMM}[9]	Input MID Voltage			V_{DD}/2– 0.2	V_{DD}/2 + 0.2	V
V_{ILL}[9]	Input LOW Voltage			–	0.4	V
I_{IL}	Input Leakage Current	V_{IN} = V_{DD}/G_{ND},V_{DD} = Max (REF and FB inputs)		–5	5	µA
I_3	3-Level Input DC Current	HIGH, V_{IN} = V_{DD}	3-Level Inputs (TEST, FS, nF[1:0], DS[1:0])	–	200	µA
		MID, V_{IN} = V_{DD}/2		–50	50	µA
		LOW, V_{IN} = V_{SS}		–200	–	µA
I_{PU}	Input Pull-up Current	V_{IN} = V_{SS}, V_{DD} = Max		–25	–	µA
I_{PD}	Input Pull-down Current	V_{IN} = V_{DD}, V_{DD} = Max, (sOE#)		–	100	µA
V_{OL}	Output LOW Voltage	I_{OL} = 12mA, (nQ[0:1])		–	0.4	V
		I_{OL} = 2mA (LOCK)			0.4	
V_{OH}	Output HIGH Voltage	I_{OH} = –12mA,(nQ[0:1])		2.0	–	V
		I_{OH} = –2mA (LOCK)		2.0		V
I_{DDQ}	Quiescent Supply Current	VDD = Max, TEST = MID, REF = LOW, sOE# = LOW, Outputs not loaded		–	2	mA
I_{DDPD}	Power-down Current	PD#, sOE# = LOW Test,nF[1:0],DS[1:0] = HIGH V_{DD} = Max		10(typ.)	25	µA
I_{DD}	Dynamic Supply Current	@100 MHz		150		mA
C_{IN}	Input Pin Capacitance			4		pF

Note:
9. These Inputs are normally wired to VDD, GND or unconnected. Internal termination resistors bias unconnected inputs to VDD/2.

DC Specifications @ 3.3V

Parameter	Description	Condition		Min.	Max.	Unit
V_{DD}	3.3 Operating Voltage	3.3V ± 10%		2.97	3.63	V
V_{IL}	Input LOW Voltage	REF, PE, PD#, FB and sOE# Inputs		–	0.8	V
V_{IH}	Input HIGH Voltage			2.0	–	V
V_{IHH}[9]	Input HIGH Voltage	3-Level Inputs (TEST, FS, nF[1:0], DS[1:0]) (These pins are normally wired to VDD,GND or unconected		V_{DD}–0.6	–	V
V_{IMM}[9]	Input MID Voltage			V_{DD}/2–0.3	V_{DD}/2+0.3	V
V_{ILL}[9]	Input LOW Voltage			–	0.6	V
I_{IL}	Input Leakage Current	V_{IN} = V_{DD}/G_{ND},V_{DD} = Max (REF and FB inputs)		–5	5	µA
I_3	3-Level Input DC Current	HIGH, V_{IN} = V_{DD}	3-Level Inputs (TEST, FS,nF[1:0], DS[1:0])	–	200	µA
		MID, V_{IN} = V_{DD}/2		–50	50	µA
		LOW, V_{IN} = V_{SS}		–200	–	µA
I_{PU}	Input Pull-Up Current	V_{IN} = V_{SS}, V_{DD} = Max		–25	–	µA
I_{PD}	Input Pull-Down Current	V_{IN} = V_{DD}, V_{DD} = Max, (sOE#)		–	100	µA
V_{OL}	Output LOW Voltage	I_{OL} = 12mA, (nQ[0:1])		–	0.4	V
		I_{OL} = 2mA (LOCK)			0.4	
V_{OH}	Output HIGH Voltage	I_{OH} = –12mA,(nQ[0:1])		2.4	–	V
		I_{OH} = –2mA (LOCK)		2.4		
I_{DDQ}	Quiescent Supply Current	VDD = Max, TEST = MID, REF = LOW, sOE# = LOW, Outputs not loaded		–	2	mA
I_{DDPD}	Power-down Current	PD#, sOE# = LOW Test,nF[1:0],DS[1:0] = HIGH V_{DD} = Max		10(typ.)	25	µA
I_{DD}	Dynamic Supply Current	@100 MHz		230		mA
C_{IN}	Input Pin Capacitance			4		pF

AC Input Specifications

Parameter	Description	Condition	Min.	Max.	Unit
T_R,T_F	Input Rise/Fall Time	0.8V – 2.0V	–	10	ns/V
T_{PWC}	Input Clock Pulse	HIGH or LOW	2	–	ns
T_{DCIN}	Input Duty Cycle		10	90	%
F_{REF}	Reference Input Frequency	FS = LOW	2	50	MHz
		FS = MID	4	100	
		FS = HIGH	8	200	

Switching Characteristics

Parameter	Description	Condition	Min.	Max.	Unit
F_{OR}	Output frequency range		6	200	MHz
VCO_{LR}	VCO Lock Range		200	400	MHz
VCO_{LBW}	VCO Loop Bandwidth		0.25	3.5	MHz
t_{SKEWPR}	Matched-Pair Skew[10]	Skew between the earliest and the latest output transitions within the same bank.	–	150	ps

Note:
10. Test Load = 20 pF, terminated to VCC/2. All outputs are equally loaded.

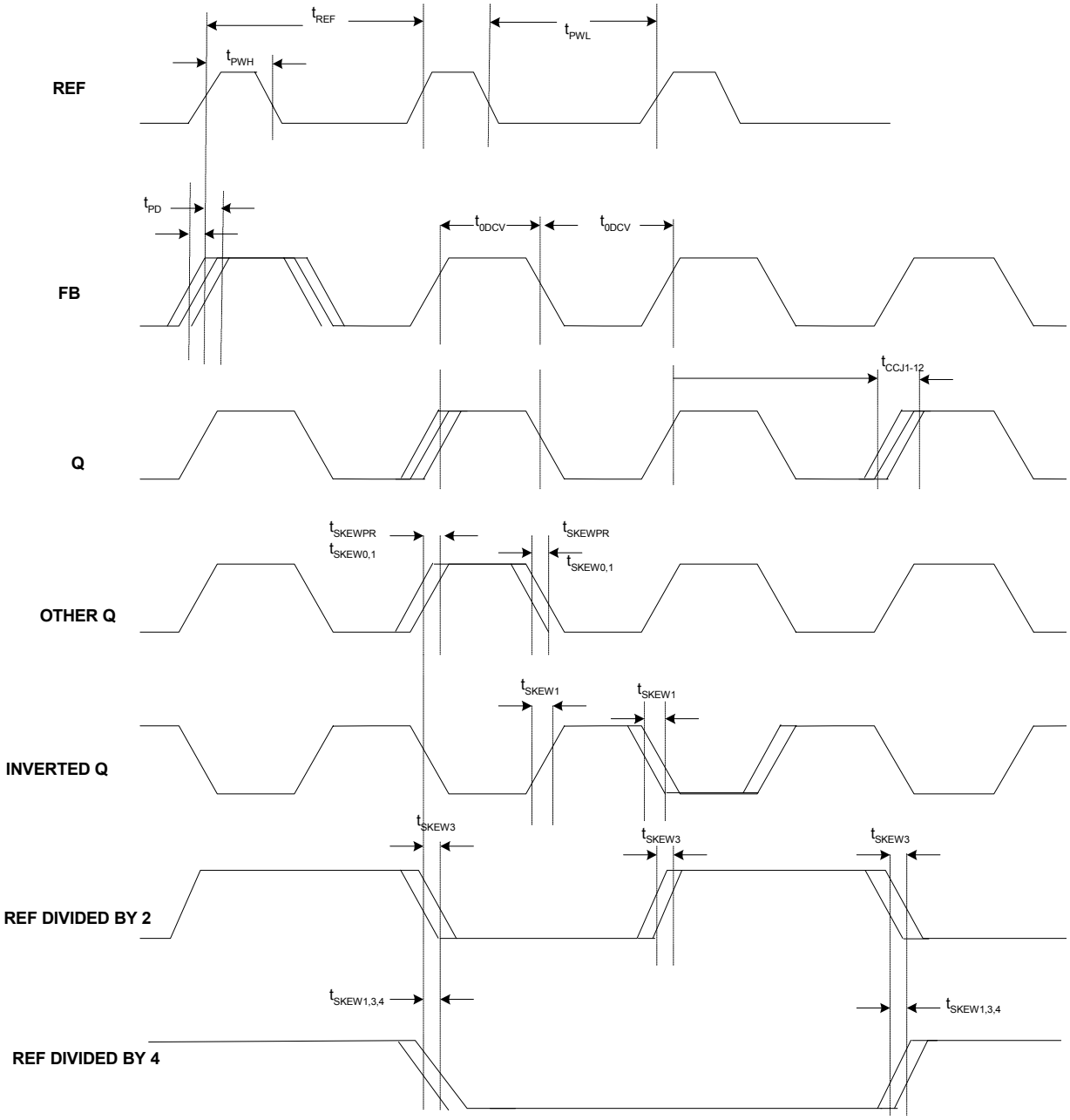
Switching Characteristics (continued)

Parameter	Description	Condition	Min.	Max.	Unit
t_{SKEW0}	Output-Output Skew[10]	Skew between the earliest and the latest output transitions among all outputs.	–	200	ps
t_{SKEW1}		Skew between the earliest and the latest output transitions among all same class outputs.	–	200	ps
t_{SKEW2}		Skew between the nominal output rising edge to the inverted output falling edge	–	500	ps
t_{SKEW3}		Skew between non-inverted outputs running at different frequencies	–	500	ps
t_{SKEW4}		Skew between nominal to inverted outputs running at different frequencies	–	500	ps
t_{SKEW5}		Skew between nominal outputs at different power supply levels	–	650	ps
t_{PART}	Part-Part Skew	Skew between the outputs of any two devices under identical settings and conditions (VDDQ,VDD,temp,air flow, frequency, etc)	–	750	ps
t_{PD0}	Ref to FB Propagation Delay[11]		–250	+250	ps
t_{ODCV}	Output Duty Cycle	Measured at VDD/2	45	55	%
t_{PWH}	Output High Time Deviation from 50%	Measured at 2.0V for VDD = 3.3V and at 1.7V for VDD = 2.5V.	–	1.5	ns
t_{PWL}	Output Low Time Deviation from 50%	Measured at 0.8V for VDD = 3.3V and at 0.7V for VDD = 2.5V.	–	2.0	ns
t_R/t_F	Output Rise/Fall Time	Measured at 0.8V-2.0V for VDD = 3.3V and 0.7V–1.7V for VDD = 2.5V	0.15	1.5	ns
t_{LOCK}	PLL lock time[12, 13]		–	0.5	ms
t_{CCJ}	Cycle-Cycle Jitter	Divide by 1 output frequency, FS = L, FB = divide by any	–	100	ps
		Divide by 1 output frequency, FS = M/H, FB = divide by any	–	150	ps

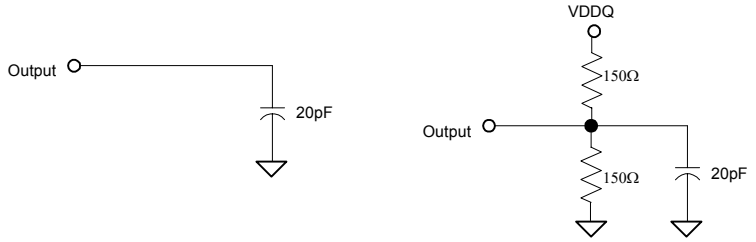
Notes:

11. t_{PD} is measured at 1.5V for VDD = 3.3V and at 1.25V for VDD = 2.5V with REF rise/fall times of 0.5 ns between 0.8V–2.0V.
12. t_{LOCK} is the time that is required before outputs synchronize to REF. This specification is valid with stable power supplies which are within normal operating limits.
13. Lock detector circuit may be unreliable for input frequencies lower than 4MHz, or for input signals which contain significant jitter.

AC Timing Definitions

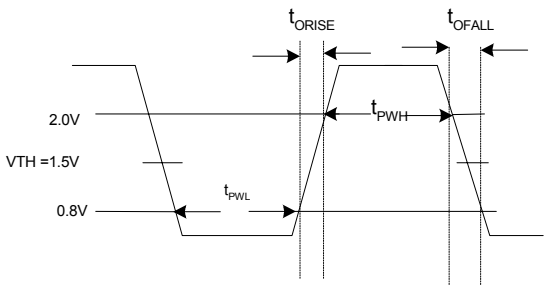


AC Test Loads and Waveforms

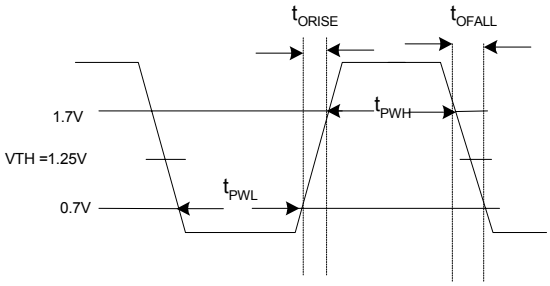


For Lock Output For All Other Outputs

Figure 1.

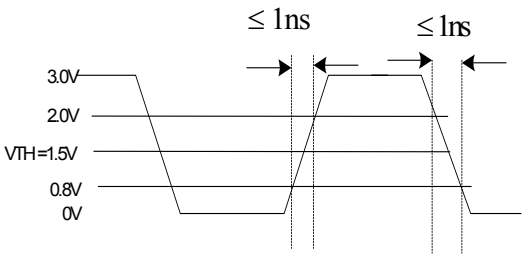


3.3V LVTTL OUTPUT WAVEFORM

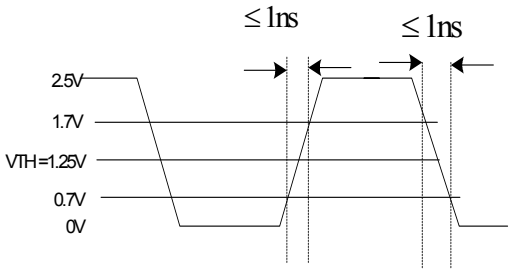


2.5V LVTTL OUTPUT WAVEFORM

Figure 2.



3.3V LVTTL INPUT TEST WAVEFORM



2.5V LVTTL INPUT TEST WAVEFORM

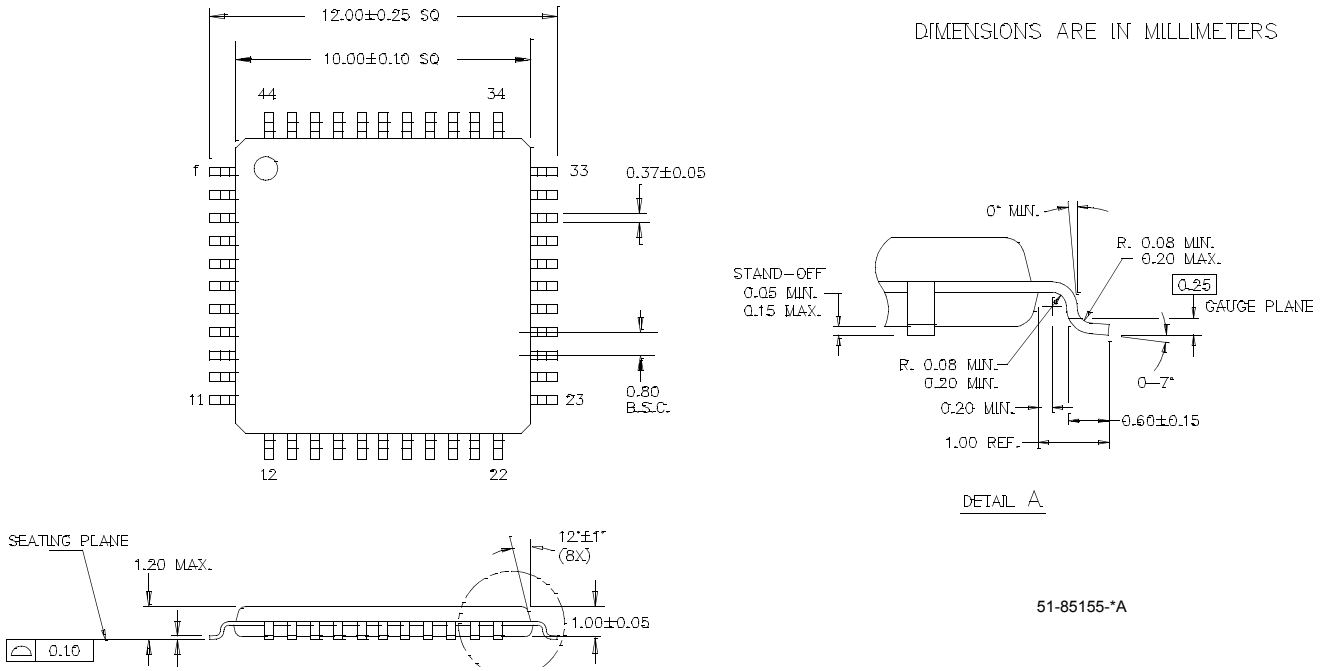
Figure 3.

Ordering Information

Part Number	Package Type	Product Flow
CY2V995AC	44 TQFP	Commercial, 0° to 70°C
CY2V995ACT	44 TQFP – Tape and Reel	Commercial, 0° to 70°C
CY2V995AI	44 TQFP	Industrial,–40° to 85°C
CY2V995AIT	44 TQFP – Tape and Reel	Industrial,–40° to 85°C

Package Drawing and Dimensions

44-lead Thin Plastic Quad Flat Pack (10 x 10 x 1.0 mm) A44SB



Document History Page

Document Title:CY2V995 2.5/3.3V 200-MHz Multi-output Zero Delay Buffer Document Number: 38-07435				
REV.	**ECN No.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	122627	01/13/03	RGL	New Data Sheet
*A	200501	See ECN	RGL	Changed Pin 5 from VDD to VDDQ4, Pin 16 from VDD to VDDQ3 and Pin 29 from VDD to VDDQ1